

Special issue on Design, Test, Integration and Packaging of MEMS and MOEMS (DTIP 2015), held in Montpellier, France, April 27–30, 2015

Pascal Nouet¹ · Bernd Michel^{2,3}

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The 2015 edition of the Symposium on Design, Test, Integration and Packaging of MEMS and MOEMS (DTIP) was held in Montpellier, France, 27–30 April 2015. Established in 1999 by our colleague Dr Bernard Courtois, DTIP is definitively the premier MEMS scientific event in Europe. DTIP'2015 was the 17th edition and has been extremely appreciated by an hundred of attendees for the quality of both scientific and social programs. Oral and poster presentations were carefully selected by the Program Committee to insure a high scientific level and awesome plenary speakers have been invited. This Symposium brought together participants interested in manufacturing of microstructures and participants interested in design tools to facilitate the design of these microstructures.

This special issue is composed of 20 extended versions of the best papers presented at the Symposium. Extended papers have been refereed, along the usual refereeing process in force at Microsystem Technologies. Selected papers cover a broad range of topics including compact thermal modelling, thermal testing, electrostatic and thermal actuation, simulation, accelerometers, electronic front-end for sensors, magnetic nanoparticles and materials, RF MEMS, Quantum dots, piezoelectric films, Micro-

transducers, magnetometers, microfluidic devices, resonant sensors, micro-fabrication, wafer bonding, Packaging, flexible interconnects and MEMS reliability.

We hope that you will enjoy these contributions as much as we did and if you want to join the DTIP community do not hesitate to attend our next event or to visit our website.

Pascal Nouet
DTIP General Chair
Guest Editor Microsystem Technologies

Bernd Michel
Editor-in-Chief, Journal Microsystem Technologies

Contact:



Pascal Nouet
dtip@dtip-mems.org
<http://www.dtip-mems.org>

✉ Pascal Nouet
nouet@lirmm.fr

Bernd Michel
office@coinn.de

¹ University of Montpellier, LIRMM, Montpellier, France

² Micro Materials Center, Berlin, Germany

³ Micro Materials Center, Chemnitz, Germany